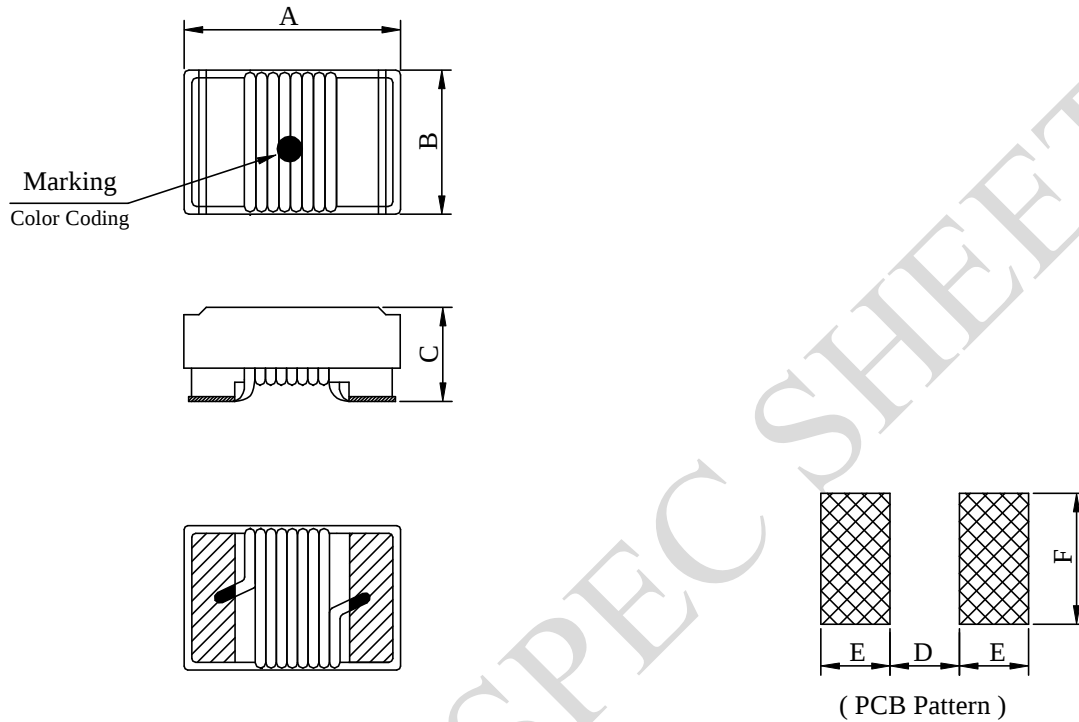


SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	Wound Chip Inductor	ABC'S DWG NO.		ESW0402□□□□L□-□□□	
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I . Configuration and dimensions :



Unit : mm

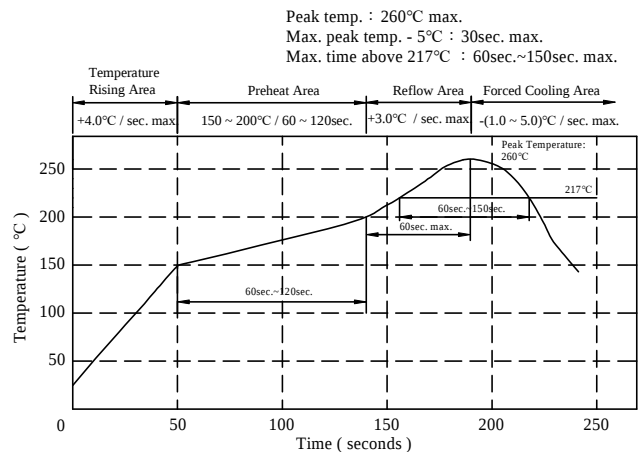
A	B	C	D	E	F
1.19 max.	0.70 max.	0.64 max.	0.46 typ.	0.36 typ.	0.66 typ.

II . Description :

- a . Powder molding construction
- b . Enamelled copper wire : H class
- c . Product weight : 0.001 g (ref.)
- d . Moisture sensitivity Level 2
- e . Products comply with RoHS' requirements
- f . Halogen free

III . General specification :

- a . Operating temp. : -40°C-----+85°C
(Temp. rise included)
- b . Resistance to solder heat : 260°C.10 sec.



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IV . Electrical characteristics :

DWG No.	Inductance (nH)	Tolerance	Q min.	Test Freq. (Hz) L & Q	SRF (GHz) min.	RDC (Ω) max.	Irms (mA) max.
ESW04021N0□L□-□□□	1.0	S,D,K,M	10	250M	12.9	0.045	1360
ESW04021N3□L□-□□□	1.3	S,D,K,M	8	250M	12.9	0.150	900
ESW04021N5□L□-□□□	1.5	S,D,K,M	8	250M	12.9	0.150	800
ESW04021N8□L□-□□□	1.8	S,D,K,M	20	250M	12.0	0.070	1040
ESW04021N9□L□-□□□	1.9	S,D,K,M	20	250M	11.3	0.070	1040
ESW04022N0□L□-□□□	2.0	J,K,M	23	250M	11.1	0.090	1040
ESW04022N2□L□-□□□	2.2	J,K,M	22	250M	10.8	0.090	960
ESW04022N4□L□-□□□	2.4	J,K,M	22	250M	10.5	0.090	790
ESW04022N6□L□-□□□	2.6	J,K,M	12	250M	10.4	0.170	400
ESW04022N7□L□-□□□	2.7	J,K,M	12	250M	10.4	0.170	400
ESW04022N9□L□-□□□	2.9	J,K,M	8	250M	8.00	0.250	400
ESW04023N0□L□-□□□	3.0	J,K,M	24	250M	7.00	0.076	840
ESW04023N3□L□-□□□	3.3	J,K,M	24	250M	7.00	0.076	840
ESW04023N6□L□-□□□	3.6	J,K,M	24	250M	6.80	0.076	840
ESW04023N9□L□-□□□	3.9	J,K,M	24	250M	6.00	0.076	840
ESW04024N1□L□-□□□	4.1	J,K,M	22	250M	6.00	0.091	700
ESW04024N3□L□-□□□	4.3	J,K,M	22	250M	6.00	0.091	700
ESW04024N7□L□-□□□	4.7	J,K,M	20	250M	4.77	0.130	640
ESW04025N1□L□-□□□	5.1	J,K,M	23	250M	4.80	0.110	800
ESW04025N6□L□-□□□	5.6	J,K,M	25	250M	4.80	0.110	760
ESW04025N8□L□-□□□	5.8	J,K,M	25	250M	4.80	0.110	760
ESW04026N2□L□-□□□	6.2	J,K,M	25	250M	4.80	0.110	760
ESW04026N8□L□-□□□	6.8	J,K,M	24	250M	4.80	0.120	680
ESW04027N2□L□-□□□	7.2	J,K,M	25	250M	4.80	0.120	680
ESW04027N3□L□-□□□	7.3	J,K,M	25	250M	4.80	0.120	680
ESW04027N5□L□-□□□	7.5	J,K,M	25	250M	4.80	0.150	680
ESW04028N2□L□-□□□	8.2	J,K,M	25	250M	4.40	0.150	680
ESW04028N7□L□-□□□	8.7	J,K,M	25	250M	4.10	0.200	480
ESW04029N0□L□-□□□	9.0	J,K,M	25	250M	4.16	0.150	680
ESW04029N1□L□-□□□	9.1	J,K,M	25	250M	4.16	0.150	680
ESW04029N5□L□-□□□	9.5	J,K,M	24	250M	4.00	0.200	480
ESW040210N□L□-□□□	10.0	J,K,M	24	250M	3.90	0.200	480
ESW040211N□L□-□□□	11.0	J,K,M	26	250M	3.68	0.120	640
ESW040212N□L□-□□□	12.0	J,K,M	26	250M	3.60	0.120	640
ESW040213N□L□-□□□	13.0	J,K,M	24	250M	3.45	0.210	440
ESW040215N□L□-□□□	15.0	J,K,M	26	250M	3.28	0.170	560
ESW040216N□L□-□□□	16.0	J,K,M	25	250M	3.10	0.250	560
ESW040218N□L□-□□□	18.0	J,K,M	25	250M	3.10	0.230	420
ESW040219N□L□-□□□	19.0	J,K,M	26	250M	3.04	0.240	480

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ABC-ATEC ELECTRONICS GROUP

SPECIFICATION FOR APPROVAL

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DWG No.	Inductance (nH)	Tolerance	Q min.	Test Freq. (Hz) L & Q	SRF (GHz) min.	RDC (Ω) max.	Irms (mA) max.
ESW040220N□L□-□□□	20.0	J,K,M	26	250M	3.00	0.250	420
ESW040222N□L□-□□□	22.0	J,K,M	25	250M	2.80	0.300	400
ESW040223N□L□-□□□	23.0	J,K,M	25	250M	2.72	0.300	400
ESW040224N□L□-□□□	24.0	J,K,M	25	250M	2.70	0.350	400
ESW040227N□L□-□□□	27.0	J,K,M	25	250M	2.48	0.300	400
ESW040230N□L□-□□□	30.0	J,K,M	25	250M	2.35	0.400	400
ESW040233N□L□-□□□	33.0	J,K,M	24	250M	2.35	0.400	400
ESW040236N□L□-□□□	36.0	J,K,M	25	250M	2.32	0.500	320
ESW040239N□L□-□□□	39.0	J,K,M	25	250M	2.10	0.550	200
ESW040240N□L□-□□□	40.0	J,K,M	24	250M	2.24	0.650	320
ESW040243N□L□-□□□	43.0	J,K,M	25	250M	2.03	0.810	100
ESW040247N□L□-□□□	47.0	J,K,M	25	250M	2.10	0.830	150
ESW040251N□L□-□□□	51.0	J,K,M	25	250M	1.75	0.920	100
ESW040256N□L□-□□□	56.0	J,K,M	25	250M	1.76	0.970	100
ESW040262N□L□-□□□	62.0	J,K,M	25	250M	1.62	1.400	100
ESW040268N□L□-□□□	68.0	J,K,M	25	250M	1.62	1.500	100
ESW040272N□L□-□□□	72.0	J,K,M	25	250M	1.26	1.700	50
ESW040275N□L□-□□□	75.0	J,K,M	25	250M	1.26	1.750	50
ESW040277N□L□-□□□	77.0	J,K,M	25	250M	1.26	1.750	50
ESW040282N□L□-□□□	82.0	J,K,M	25	250M	1.26	1.800	50
ESW040291N□L□-□□□	91.0	J,K,M	24	250M	1.16	2.200	30
ESW0402R10□L□-□□□	100.0	G,J,K,M	24	250M	1.16	2.500	30
ESW0402R11□L□-□□□	110.0	G,J,K,M	24	250M	1.15	2.600	30
ESW0402R12□L□-□□□	120.0	G,J,K,M	24	250M	1.10	2.200	30
ESW0402R15□L□-□□□	150.0	G,J,K,M	10	250M	1.00	4.000	20

- 1). Electrical specifications at 25°C
- 2). Irms base on temp. rise 40°C typ.
- 3). Tolerance : S(±0.3) 、 D(±0.5) 、 G(±2%) 、 J(±5%) 、 K(±10%) 、 M(±20%)

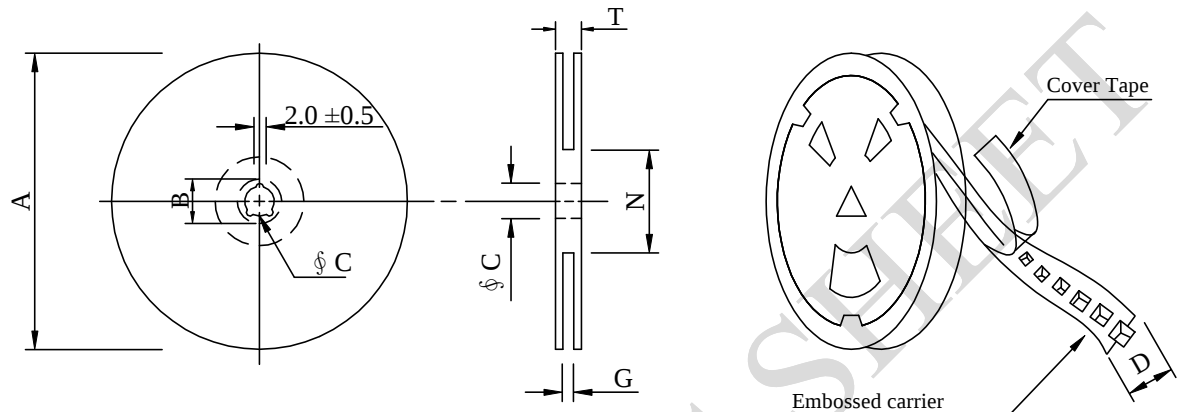
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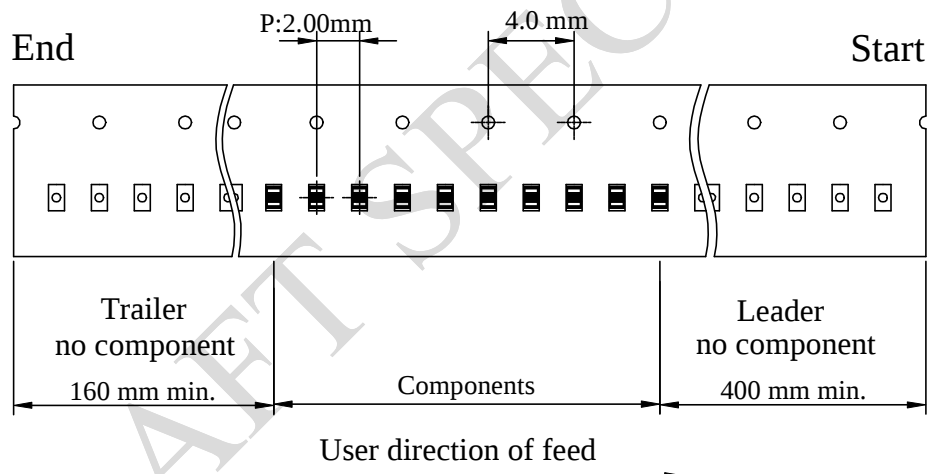
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V . Packaging information :

(1) Configuration



※Carrier tape width : D



(2) Dimensions

Unit:mm

Style	A	B	C	D	G	N	T
07 - 08	178	21	13	8	8.4 ⁺⁰	60 ⁻⁰	12.4

(3) Q'TY & G.W. Per package

Code	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (g)	Style	Q'TY (pcs)	G.W. (kg)	Size (cm)
B	10,000	160	07 - 08	500,000	9.25	39.5 x 39.5 x 23

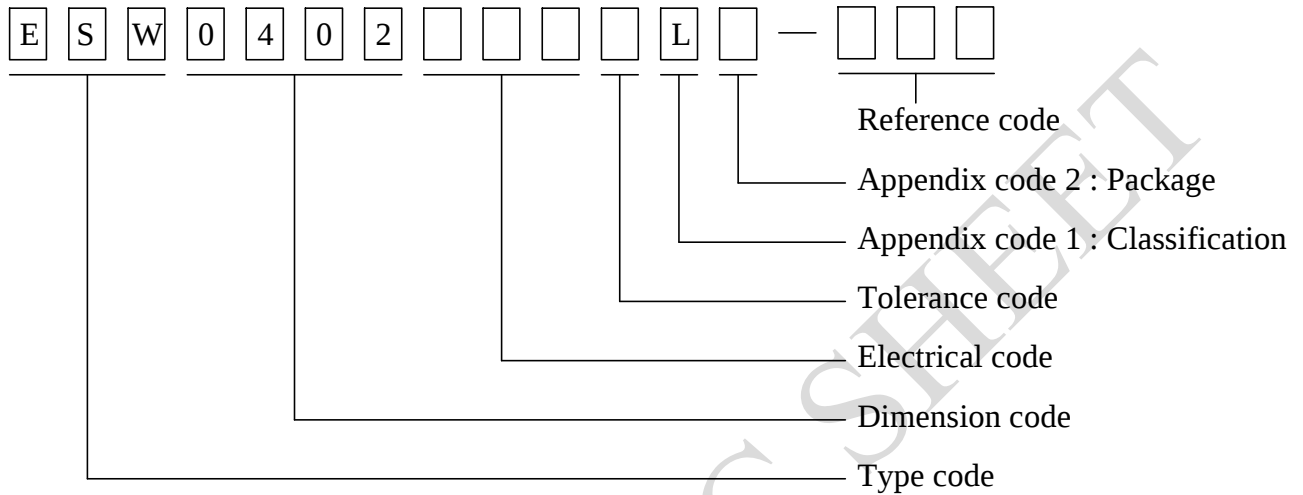
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VI . Drawing number expression :



Appendix code 1 : Product Classification

Appendix code 2 : Package Information

Code	Inner package	Cover tape	Carrier tape	Bag	Package Q'TY	Remark
B	T /R (Reel package)	NA	NA	NA	10,000 pcs	

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VII . Safety notes :

1. Products do not be used in related applications that directly affect the personal safety system or cause significant impacts and losses on society. If you apply to these applications, please be sure to contact us at first to confirm.
產品不可使用於直接影響人身安全系統或對社會會造成重大影響與損失之相關用途，若您應用於此，請務必優先與我們聯繫確認。
2. The storage period is less than 12 months. Ensure to follow the storage conditions (Temperature: 5 to 30°C, Humidity: 10 to 60% RH or less). If the storage time is exceeded the limit, the electrodes might be deteriorate of terminal soldering.
儲存期不超過12個月，務必遵守儲存條件（溫度：5至30°C，濕度：10至60%RH以下）。如果超過了儲存時間，端子電極可能會氧化而影響焊接。
3. Do not use or store in locations where there are conditions such as gas corrosion (salt, acid, alkali, etc.).
不要在有氣體腐蝕等條件的地方使用或存放（鹽，酸，鹼等）。
4. Soldering corrections after mounting should be within the range of the conditions determined in the specifications. If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
安裝時的焊接條件應在規格範圍內。如果超過要求，可能會發生短路，性能下降或壽命縮短。
5. When using, it should try to avoid excessive mechanical impact on the product, such as collision / drop ... and other reasons.
使用時，應盡量避免產品受到過度機械衝擊，如碰撞/掉落...等原因。
6. When embedding a printed circuit board where a chip is mounted to a set, be sure that residual stress is not given to the chip due to the overall distortion of the printed circuit board and partial distortion such as at screw tightening portions.
將已安裝新片的電路板組裝到裝置時，請注意應盡量避免電路板受到組裝變形...等，導致產品受到應力。
7. Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
產品會因通電而自我發熱(溫度上升)，因此在熱影響設計方面，需保留適當公差。
8. Do not expose the products to magnets or magnetic fields.
請勿將產品暴露於磁鐵或是磁場中。
9. If you would like to use this products to performance and/or quality require a more stringent level of safety or reliability, or whose failure, malfunction or trouble could cause serious damage to society, person or property, or if you have special requirements exceeding the range or conditions set forth in the each catalog, please contact us.
如果您希望將此產品用於性能和/或質量要求更嚴格的安全性或可靠性，或其失敗、故障或麻煩可能對社會、個人或財產造成嚴重損害，或者您有特殊情況要求超出目錄中規定的範圍或條件，請與我們聯繫。